

PRESS RELEASE

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Three Critical Days, Three Design Pavilions, Three Industry Luminaries The Value of ARM® techcon³ Continues to Multiply

San Clemente, CA - Formerly known as ARM Developers' Conference, the 2009 ARM® techcon³ is expanding its focus to three important areas of design which include Energy Efficiency, Internet Everywhere and MCU & Tools. The event will be held October 21-23, 2009 at the Santa Clara Convention Center.

Keeping in line with the event's theme, Design to the Power of Three, ARM® techcon³ features a Technical Chair Committee with three experts that combine for more than 75 years of knowledge within the industry. Serving as the overall Technical Chair, Brian Fuller teams up with Co-Chairs John Donovan and Tom Starnes to navigate this multi-dimensional event's three critical segments.

Fuller, a writer, editor and communications consultant, brings 25 years worth of journalism and new-media experience to the committee. Most recently serving as senior vice president for Digital Media and Content Creation at Blanc & Otus, he channeled his expertise to help clients achieve business goals based on social media.

Prior to Blanc & Otus, Fuller spent 15 years with *EE Times*, the last six as editor-in-chief. Throughout his tenure with CMP, he transformed *EE Times* into one of the most trusted resources within the electronics industry; he also helped create a dominating online presence for the franchise. As the brainpower behind one of the first industry-related blogs as well as podcasts and video coverage, Fuller is considered a pioneer for the online identity of the electronics industry. Today, he writes about issues within the electronics market as well as communications strategies on his blog, Greeley's Ghost, while speaking and moderating panels at various industry events.

Serving as an ARM® techcon³ Co-Chair, John Donovan will represent the Energy Efficiency Pavilion. Donovan, formerly the editor-in-chief of *Portable Design* magazine, has spent over 25 years as a technical writer. He was also an editor at *EDN Asia*, *Circuits Assembly Asia* and *PC Fabrication Asia* with additional time spent as a correspondent for *Byte Magazine* and as a columnist for *Electronic Business Asia*.

Donovan is the editor of *Portable Electronics*, part of the World Class Designs series, in which he addresses the fundamentals of design as well as solutions to common design problems. As a familiar industry resource, Donovan brings a wealth of insight and experience to the event.

Rounding out the Technical Chair Committee and directing the Internet Everywhere and MCU & Tools Pavilions is Tom Starnes, an analyst for the embedded processor industry for more than 25 years. Well-versed as an author, speaker and advisor, Starnes focuses on architectures, products, vendors, markets, and end-uses of processors, watching for trends, winners, and losers.

As the processor analyst for Objective Analysis, an independent market research firm, Starnes' unique insight on applications, competition and outlook is offered to vendors, third-parties, users, OEMs, and the financial community. He has also become a valuable resource regarding business opportunities and technical evaluation.

ARM® techcon³ is brought to the engineering community by The RTC Group and Convergence Promotions in partnership with the ARM technology ecosystem and is the largest gathering of ARM developers and partners in the world.

Industry experts are invited and encouraged to take advantage of a special opportunity to present at ARM® techcon³ through seminar sessions, training workshops, and/or a panel discussions. Space is limited and the deadline is July 14 for those interested in submitting an abstract for consideration.

For more information, please visit www.armtechcon3.com.